



Pb-free
HEAT



1105W Series

Single Color 3216 Dome Lenz Type

Features

Package	3216 Dome Lens Type, Water Clear resin										
Product features	• Outer Dimension 3.2 x 1.6 x 1.85mm (L x W x H) • Temperature range - Storage Temperature : -40℃~100℃ - Operating Temperature : -40℃~120℃ • Lead-free soldering compatible • RoHS compliant										
Dominant wavelength	<table><tr><td>Green</td><td>: 558nm(HBG),567nm(HPG)</td></tr><tr><td>Yellow Green</td><td>: 572nm(HPY)</td></tr><tr><td>Yellow</td><td>: 590nm(HAY)</td></tr><tr><td>Orange</td><td>: 606nm(HAA)</td></tr><tr><td>Red</td><td>: 647nm(HBR)</td></tr></table>	Green	: 558nm(HBG),567nm(HPG)	Yellow Green	: 572nm(HPY)	Yellow	: 590nm(HAY)	Orange	: 606nm(HAA)	Red	: 647nm(HBR)
Green	: 558nm(HBG),567nm(HPG)										
Yellow Green	: 572nm(HPY)										
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Red	: 647nm(HBR)										
Half Intensity Angle	<table><tr><td>HBG,HPG,HPY,HAY,HAA</td><td>: 40 deg.</td></tr><tr><td>HBR</td><td>: 50 deg.</td></tr></table>	HBG,HPG,HPY,HAY,HAA	: 40 deg.	HBR	: 50 deg.						
HBG,HPG,HPY,HAY,HAA	: 40 deg.										
HBR	: 50 deg.										
Die materials	<table><tr><td>HBG,HPG,HPY</td><td>: GaP</td></tr><tr><td>HAY,HAA</td><td>: GaAsP</td></tr><tr><td>HBR</td><td>: GaAlAs</td></tr></table>	HBG,HPG,HPY	: GaP	HAY,HAA	: GaAsP	HBR	: GaAlAs				
HBG,HPG,HPY	: GaP										
HAY,HAA	: GaAsP										
HBR	: GaAlAs										
Rank grouping parameter	Sorted by luminous intensity per rank taping										
Assembly method	Auto pick & place machine (Auto Mounter)										
Soldering methods	Reflow soldering and manual soldering										
Taping and reel	2,000pcs per reel in a 8mm width tape. (Standard) Reel diameter: ϕ 180mm										
ESD	More than 2kV (HBM)										

Recommended Applications

Amusement Equipment, Electric Household Appliances, OA/FA, Other General Applications

Color and Luminous Intensity

(Ta=25°C)

Part No.	Material	Emitted Color	Lens Color	Dominant Wavelength λ_d (nm)		Luminous Intensity I_v (mcd)		
				TYP.	I_f	MIN.	TYP.	I_f
HBG1105W	GaP	Green	Water Clear	558	20	6	12	20
HPG1105W	GaP	Green		567	20	15	30	20
HPY1105W	GaP	Yellow Green		572	20	20	50	20
HAY1105W	GaAsP	Yellow		590	20	10	20	20
HAA1105W	GaAsP	Orange		606	20	10	20	20
HBR1105W	GaAlAs	Red		647	20	25	50	20

Absolute Maximum Ratings

(Ta=25°C)

Item	Symbol	Absolute Maximum Ratings						Unit
		HBG	HPG	HPY	HAY	HAA	HBR	
Power Dissipation	P_d	75	75	75	75	75	60	mW
Forward Current	I_F	30	30	30	30	30	30	mA
Pulse Forward Current ※1	I_{FRM}	70	70	70	70	70	70	mA
Derating (Ta=75°C or higher)	ΔI_F	1.00	1.00	1.00	1.00	1.00	1.00	mA/°C
	ΔI_{FRM}	0.29	2.33	2.33	2.33	2.33	2.33	mA/°C
Reverse Voltage	V_R	4	4	4	4	4	4	V
Operating Temperature	T_{opr}	-40~+100						°C
Storage Temperature	T_{stg}	-40~+120						°C

※1 I_{FRM} Measurement condition : Pulse Width ≤ 1 ms., Duty $\leq 1/20$.

Electro-Optical Characteristics

(Ta=25°C)

Item	Conditions	Symbol	Characteristics							Unit
				HBG	HPG	HPY	HAY	HAA	HBR	
Forward Voltage	I _F =20mA	V _F	TYP.	2.1	2.1	2.1	2.2	2.2	1.7	V
			MAX.	2.5	2.5	2.5	2.5	2.5	2.0	
Reverse Current	V _R =4V	I _R	MAX.	100	100	100	100	100	100	μ A
Peak Wavelength	I _F =20mA	λ _p	TYP.	555	560	570	580	605	660	nm
Dominant Wavelength	I _F =20mA	λ _d	TYP.	558	567	572	590	606	647	nm
Spectral Line Half Width	I _F =20mA	Δλ	TYP.	30	30	30	30	30	30	nm
Half Intensity Angle	I _F =20mA	2θ 1/2	TYP.	40	40	40	40	40	50	deg.

Luminous Intensity Rank

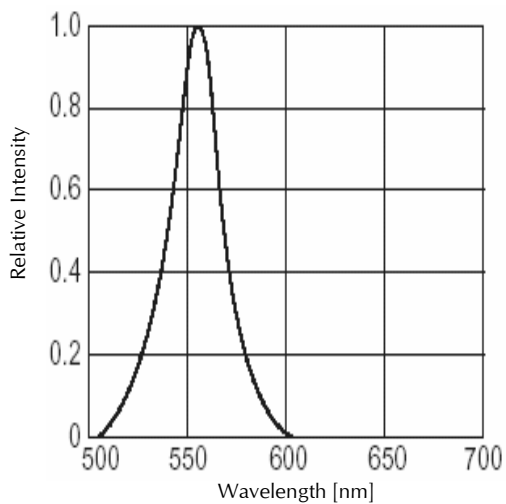
(Ta=25°C)

Rank	I _v (mcd)											
	HBG		HPG		HPY		HAY		HAA		HBR	
	I _F =20mA		I _F =20mA		I _F =20mA		I _F =20mA		I _F =20mA		I _F =20mA	
	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.
A	6.0	12.0	15.0	30.0	20.0	40.0	10.0	20.0	10.0	20.0	25.0	50.0
B	8.5	17.0	21.0	42.0	28.0	56.0	14.0	28.0	14.0	28.0	35.0	70.0
C	12.0	24.0	30.0	60.0	40.0	80.0	20.0	40.0	20.0	40.0	50.0	100.0
D	17.0	34.0	42.0	84.0	56.0	112.0	28.0	56.0	28.0	56.0	70.0	140.0
E	24.0	-	60.0	-	80.0	-	40.0	-	40.0	-	100.0	-

※ Please contact our sales staff concerning rank designation.

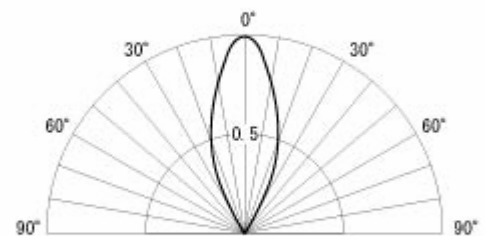
Technical Data(HBG)

Spectral Distribution
Relative Intensity vs. Wavelength
Condition : $T_a = 25^\circ\text{C}$, $I_F = 20\text{mA}$

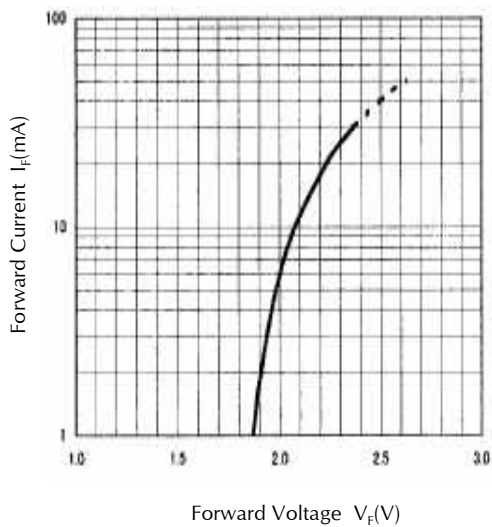


Spatial Distribution Example

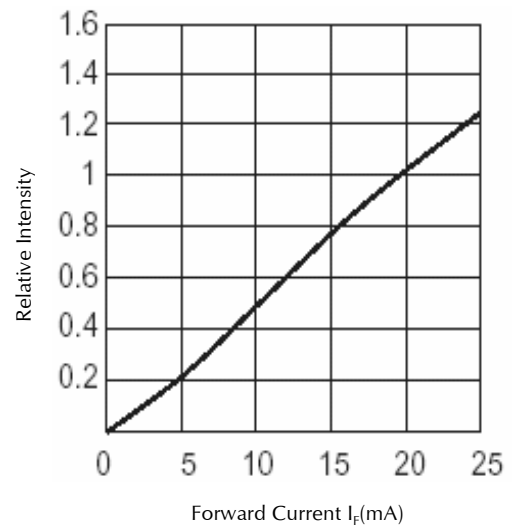
Condition : $T_a = 25^\circ\text{C}$



Forward Voltage vs. Forward Current
Condition : $T_a = 25^\circ\text{C}$



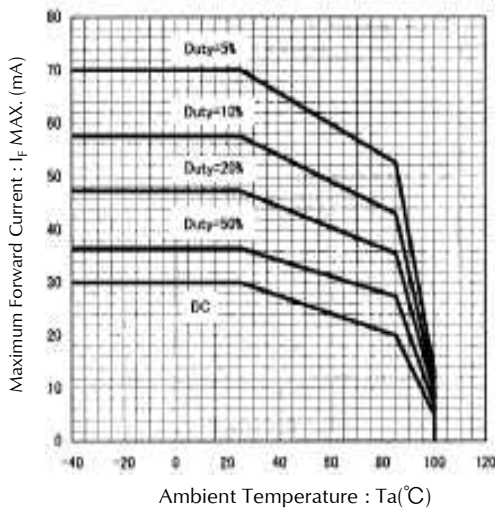
Forward Current vs. Relative Intensity
Condition : $T_a = 25^\circ\text{C}$



Technical Data(HBG)

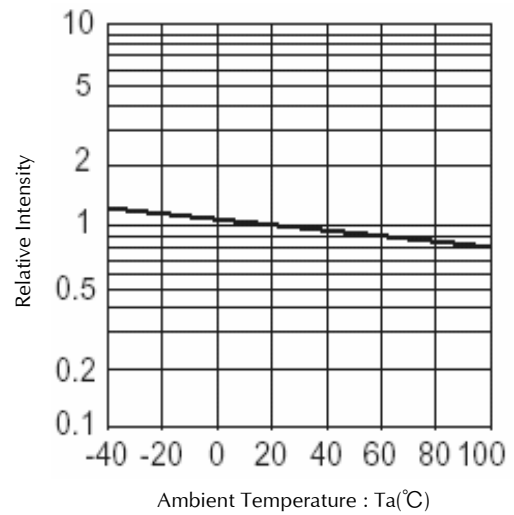
Derating

Ambient Temperature vs. Maximum Forward Current
Repetition Frequency : $f \geq 50\text{Hz}$

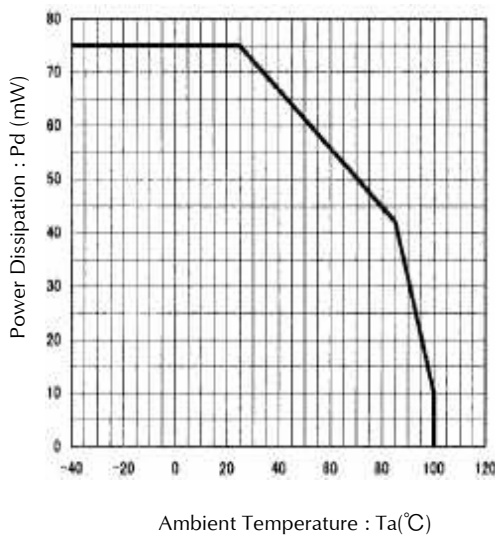


Ambient Temperature vs. Relative Intensity

Condition : $I_F=20\text{mA}$

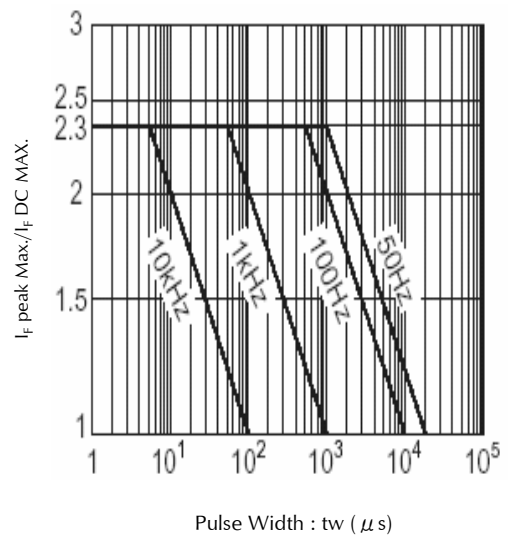


Power Dissipation vs. Ambient Temperature



Pulse Width vs. Maximum Tolerable Peak Current

Condition : $T_a = 25^{\circ}\text{C}$

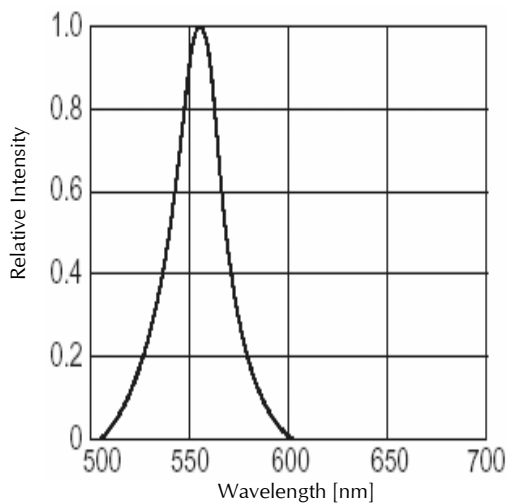


Technical Data(HPG)

Spectral Distribution

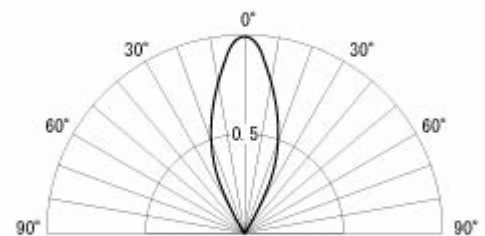
Relative Intensity vs. Wavelength

Condition : $T_a = 25^\circ\text{C}$, $I_F = 20\text{mA}$



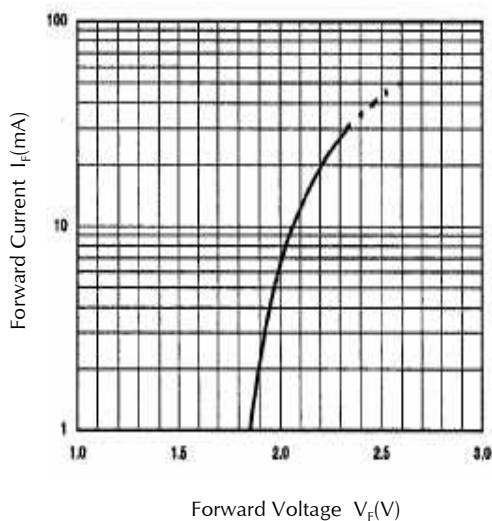
Spatial Distribution Example

Condition : $T_a = 25^\circ\text{C}$



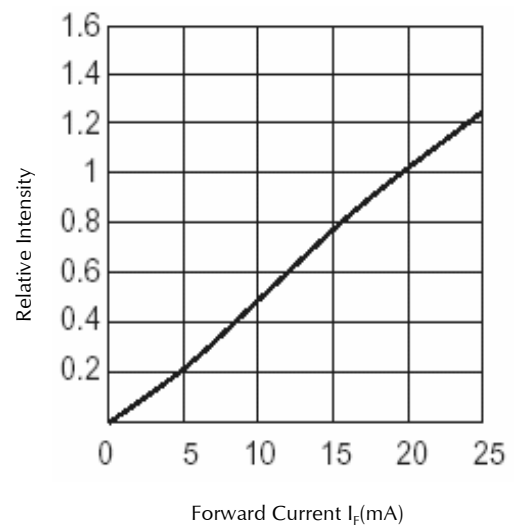
Forward Voltage vs. Forward Current

Condition : $T_a = 25^\circ\text{C}$



Forward Current vs. Relative Intensity

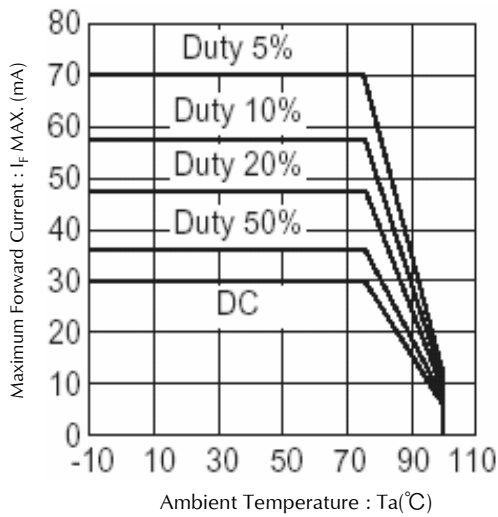
Condition : $T_a = 25^\circ\text{C}$



Technical Data(HPG)

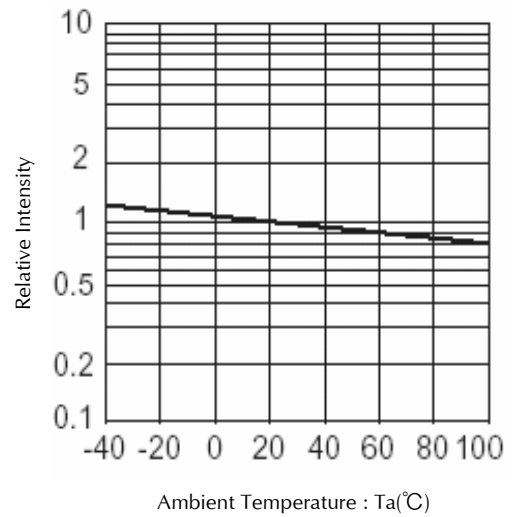
Derating

Ambient Temperature vs. Maximum Forward Current
Repetition Frequency : $f \geq 50\text{Hz}$

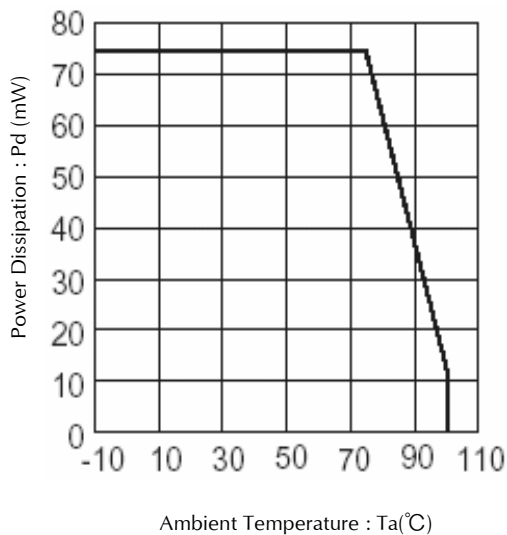


Ambient Temperature vs. Relative Intensity

Condition : $I_F = 20\text{mA}$

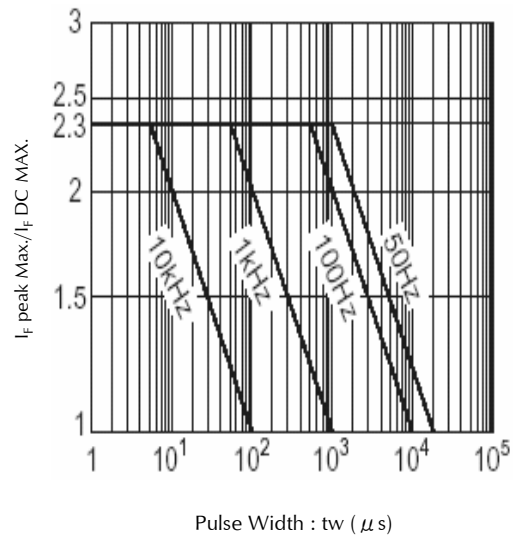


Power Dissipation vs. Ambient Temperature



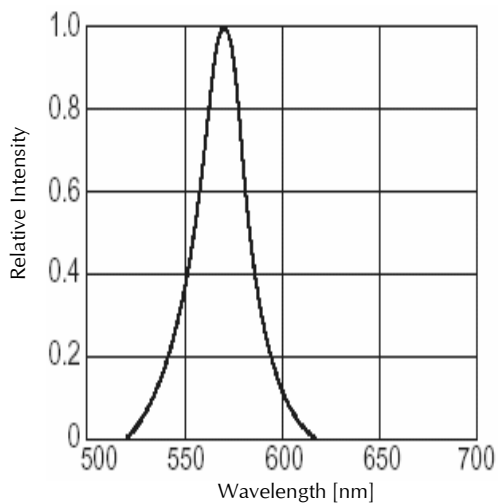
Pulse Width vs. Maximum Tolerable Peak Current

Condition : $T_a = 25^\circ\text{C}$



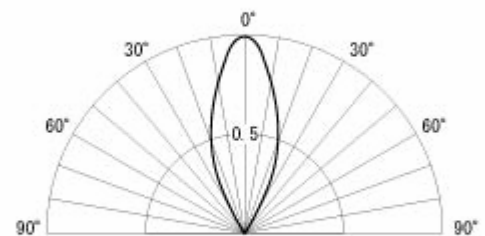
Technical Data(HPY)

Spectral Distribution
Relative Intensity vs. Wavelength
Condition : $T_a = 25^\circ\text{C}$, $I_F = 20\text{mA}$

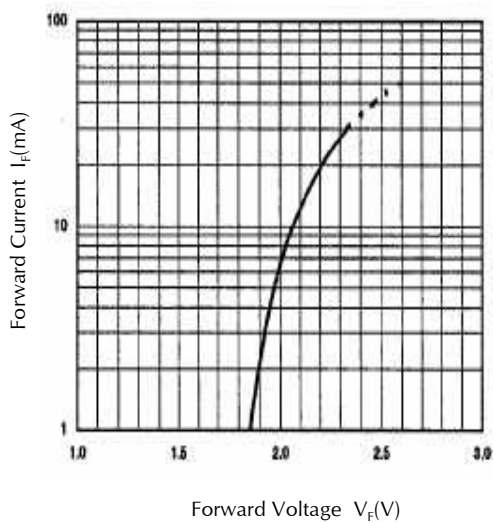


Spatial Distribution Example

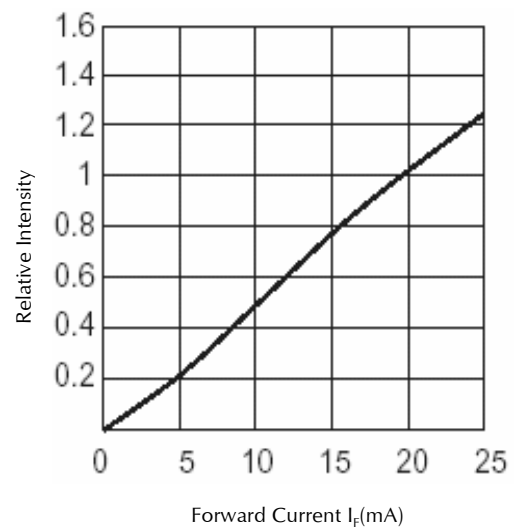
Condition : $T_a = 25^\circ\text{C}$



Forward Voltage vs. Forward Current
Condition : $T_a = 25^\circ\text{C}$



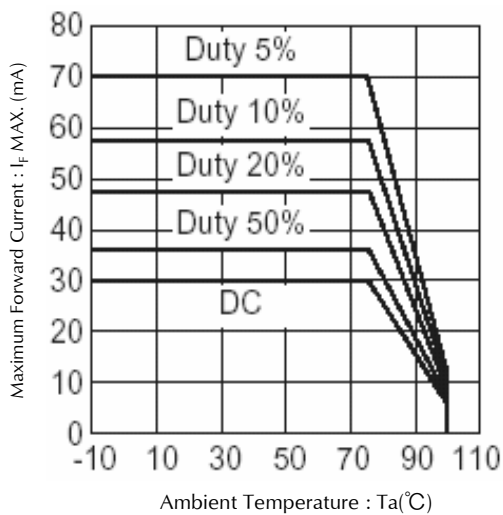
Forward Current vs. Relative Intensity
Condition : $T_a = 25^\circ\text{C}$



Technical Data(HPY)

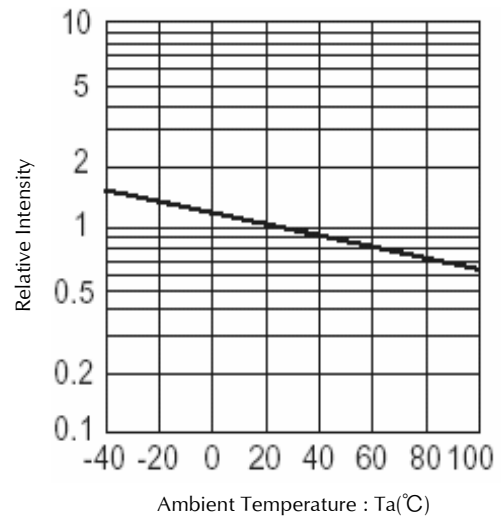
Derating

Ambient Temperature vs. Maximum Forward Current
Repetition Frequency : $f \geq 50\text{Hz}$

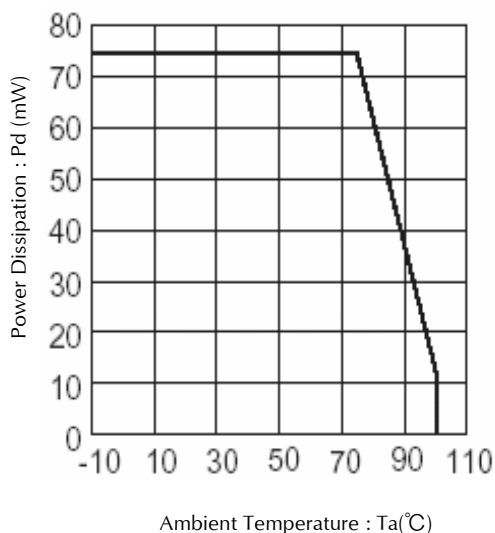


Ambient Temperature vs. Relative Intensity

Condition : $I_F = 20\text{mA}$

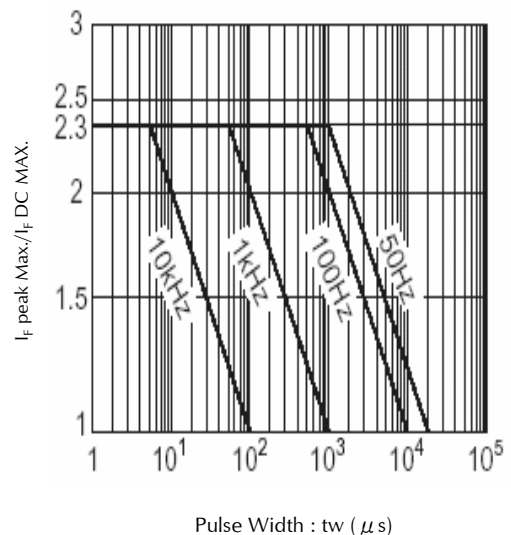


Power Dissipation vs. Ambient Temperature



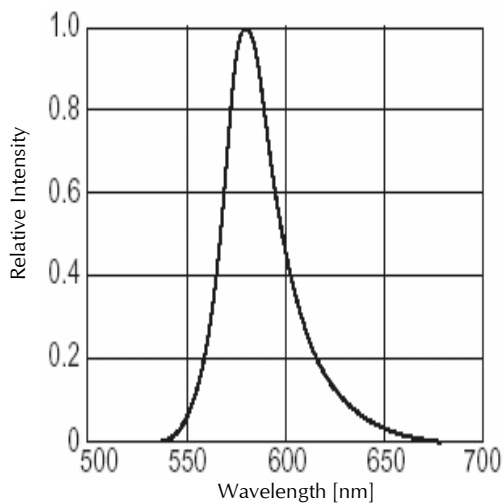
Pulse Width vs. Maximum Tolerable Peak Current

Condition : $T_a = 25^{\circ}\text{C}$



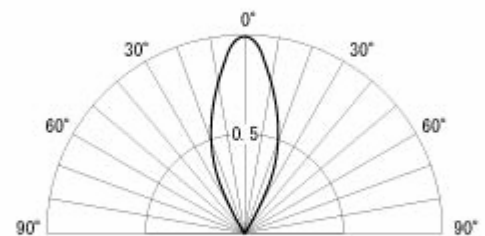
Technical Data(HAY)

Spectral Distribution
Relative Intensity vs. Wavelength
Condition : $T_a = 25^\circ\text{C}$, $I_F = 20\text{mA}$

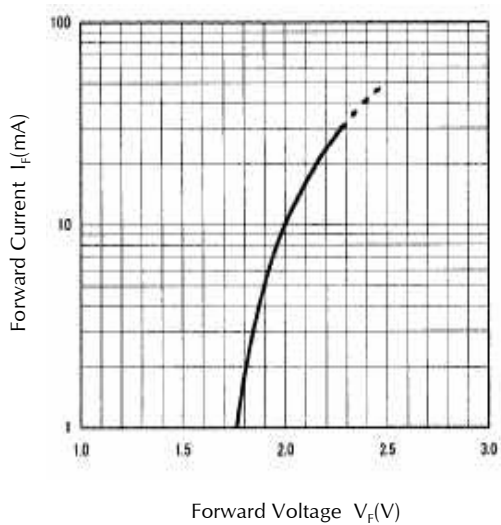


Spatial Distribution Example

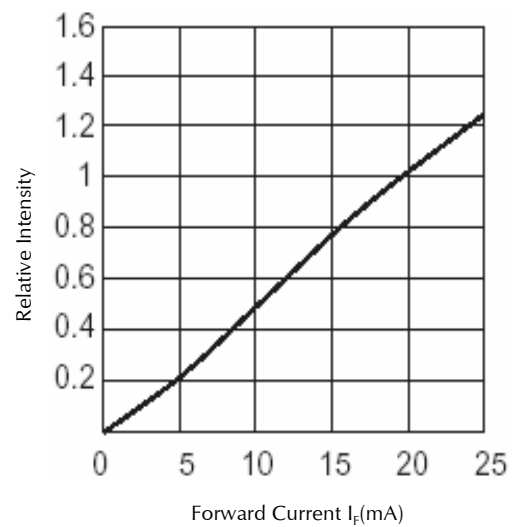
Condition : $T_a = 25^\circ\text{C}$



Forward Voltage vs. Forward Current
Condition : $T_a = 25^\circ\text{C}$



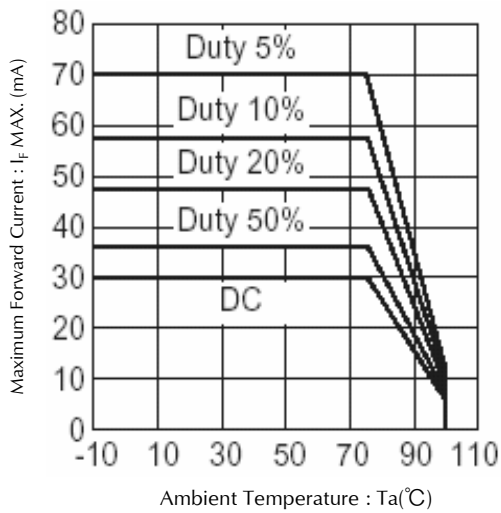
Forward Current vs. Relative Intensity
Condition : $T_a = 25^\circ\text{C}$



Technical Data(HAY)

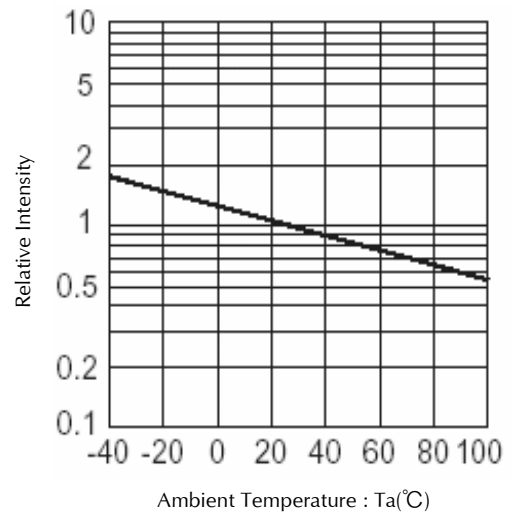
Derating

Ambient Temperature vs. Maximum Forward Current
Repetition Frequency : $f \geq 50\text{Hz}$

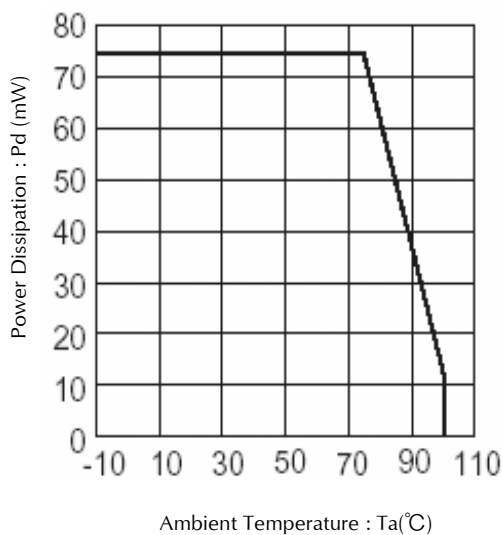


Ambient Temperature vs. Relative Intensity

Condition : $I_F = 20\text{mA}$

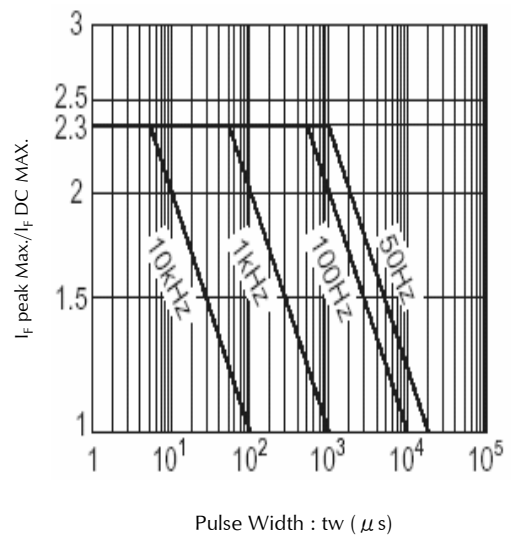


Power Dissipation vs. Ambient Temperature



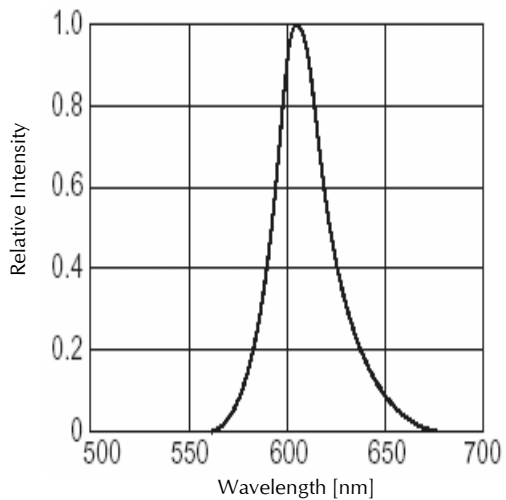
Pulse Width vs. Maximum Tolerable Peak Current

Condition : $T_a = 25^\circ\text{C}$



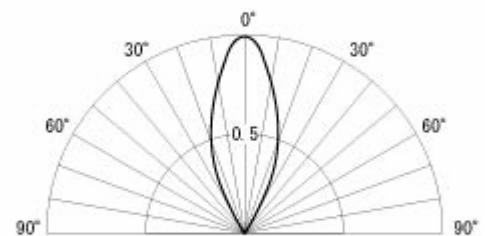
Technical Data(HAA)

Spectral Distribution
Relative Intensity vs. Wavelength
Condition : $T_a = 25^\circ\text{C}$, $I_F = 20\text{mA}$

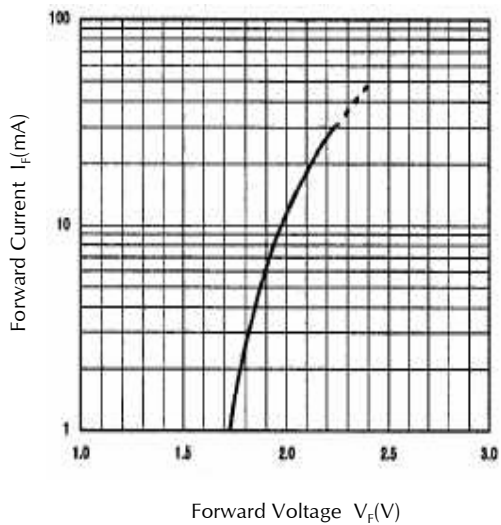


Spatial Distribution Example

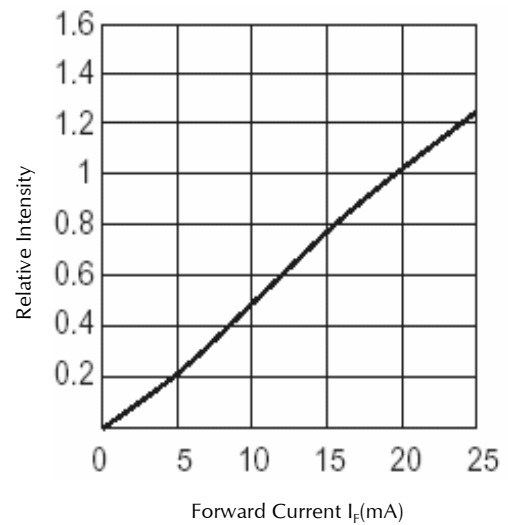
Condition : $T_a = 25^\circ\text{C}$



Forward Voltage vs. Forward Current
Condition : $T_a = 25^\circ\text{C}$



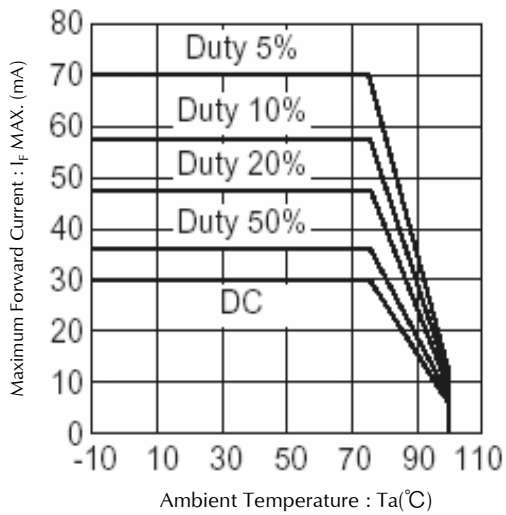
Forward Current vs. Relative Intensity
Condition : $T_a = 25^\circ\text{C}$



Technical Data(HAA)

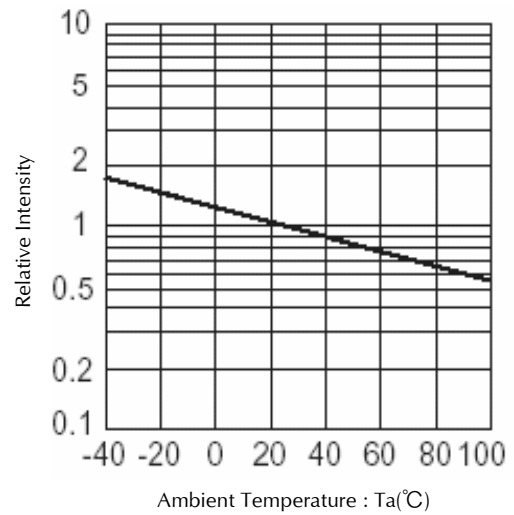
Derating

Ambient Temperature vs. Maximum Forward Current
Repetition Frequency : $f \geq 50\text{Hz}$

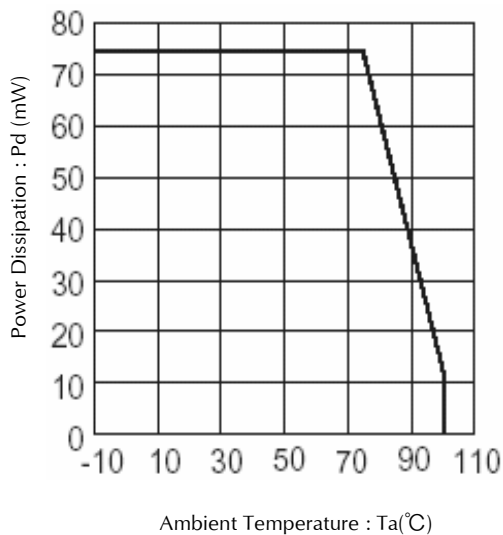


Ambient Temperature vs. Relative Intensity

Condition : $I_F = 20\text{mA}$

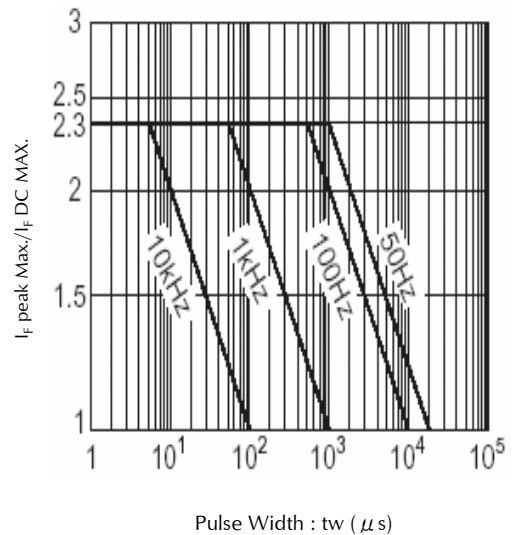


Power Dissipation vs. Ambient Temperature



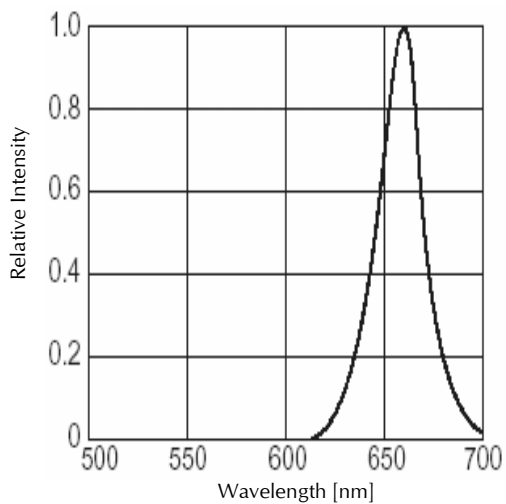
Pulse Width vs. Maximum Tolerable Peak Current

Condition : $T_a = 25^\circ\text{C}$



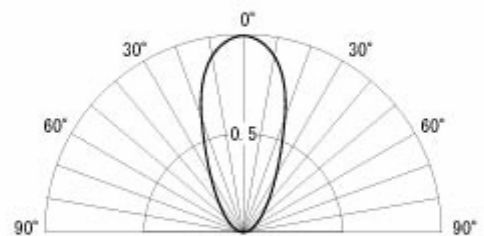
Technical Data(HBR)

Spectral Distribution
Relative Intensity vs. Wavelength
Condition : $T_a = 25^\circ\text{C}$, $I_F = 20\text{mA}$

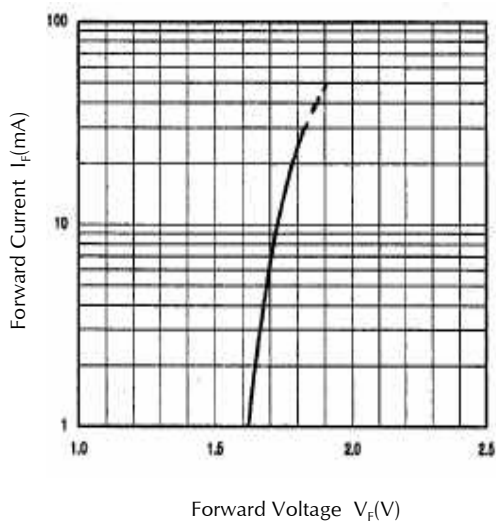


Spatial Distribution Example

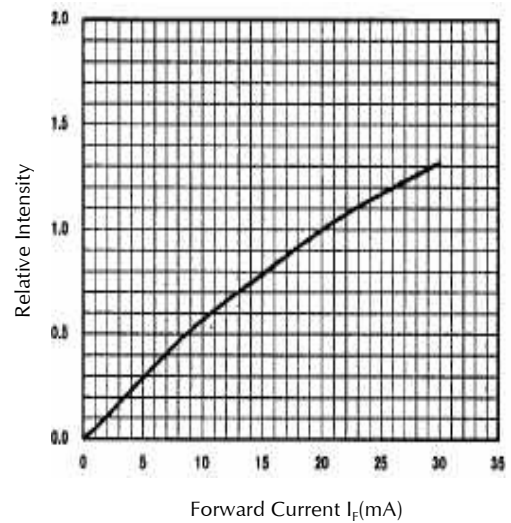
Condition : $T_a = 25^\circ\text{C}$



Forward Voltage vs. Forward Current
Condition : $T_a = 25^\circ\text{C}$



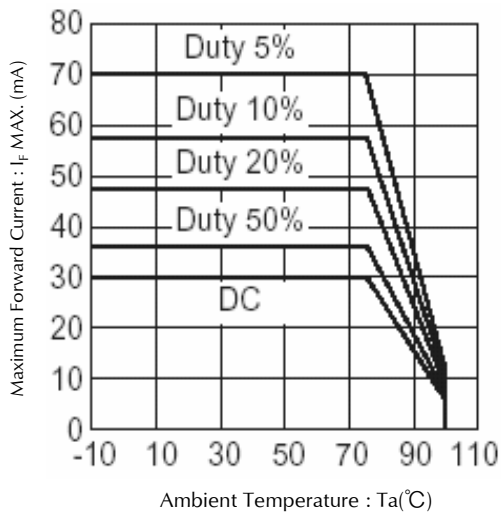
Forward Current vs. Relative Intensity
Condition : $T_a = 25^\circ\text{C}$



Technical Data(HBR)

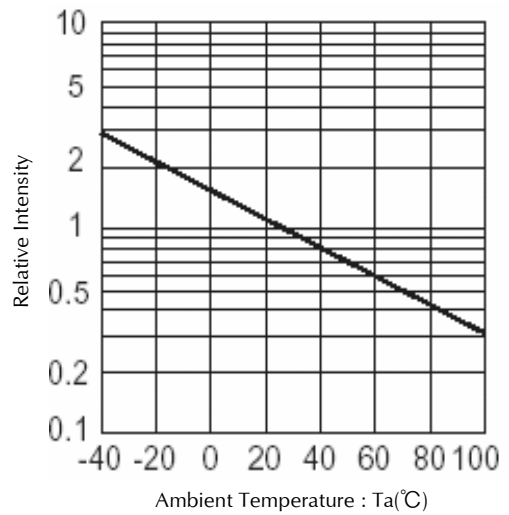
Derating

Ambient Temperature vs. Maximum Forward Current
Repetition Frequency : $f \geq 50\text{Hz}$

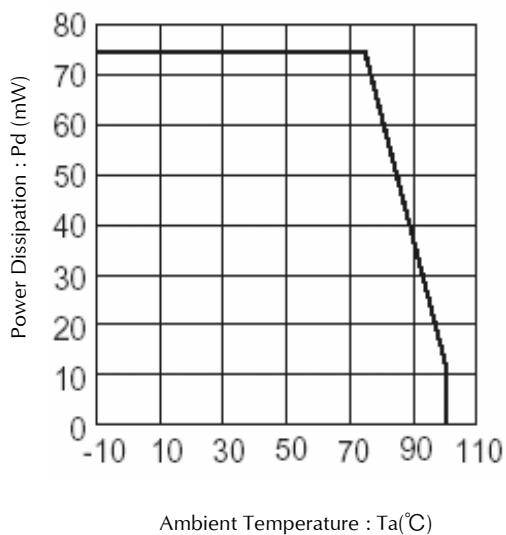


Ambient Temperature vs. Relative Intensity

Condition : $I_F = 20\text{mA}$

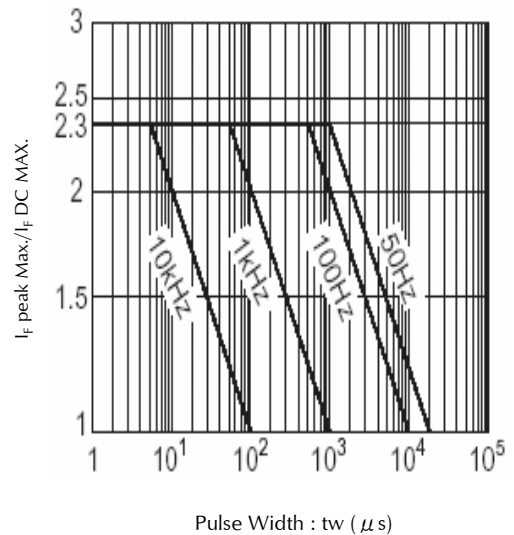


Power Dissipation vs. Ambient Temperature



Pulse Width vs. Maximum Tolerable Peak Current

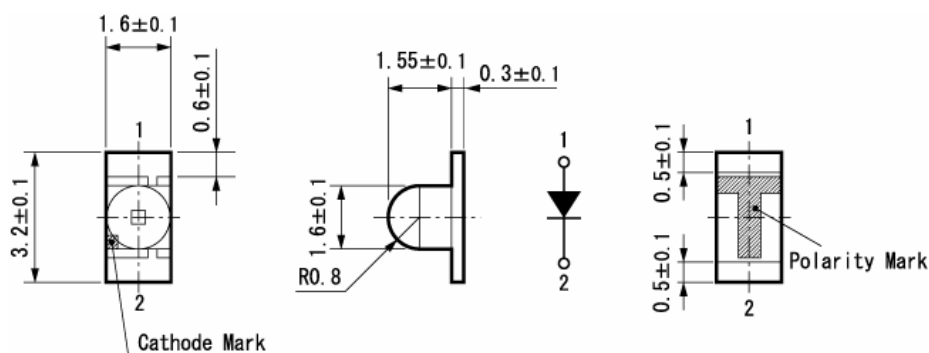
Condition : $T_a = 25^{\circ}\text{C}$



Package Dimensions

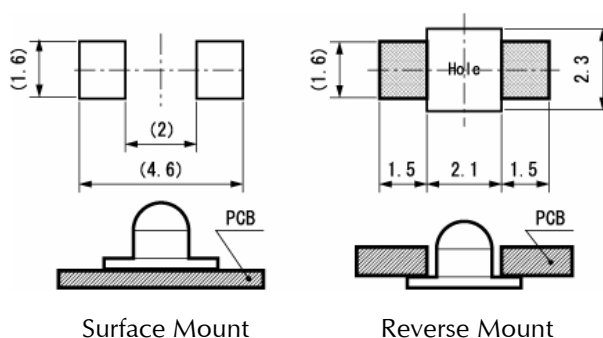
(Unit: mm)

Weight: (7.81)mg



Recommended Soldering Pattern

(Unit: mm)

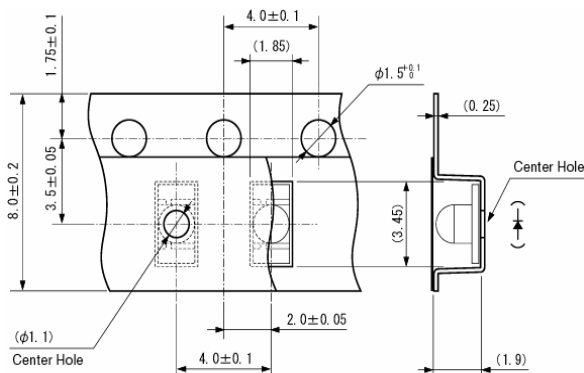


Taping Specification

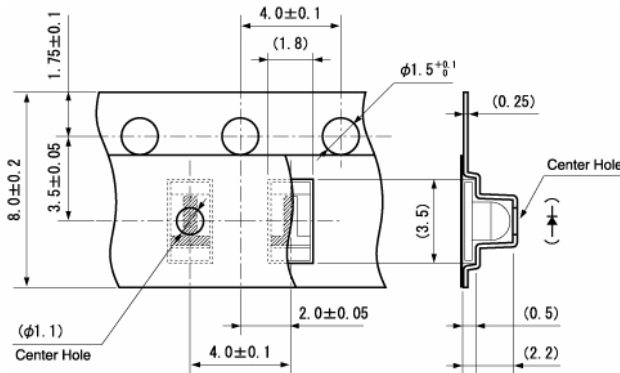
(Unit: mm)

Quantity : 2,000pcs/ reel (standard)

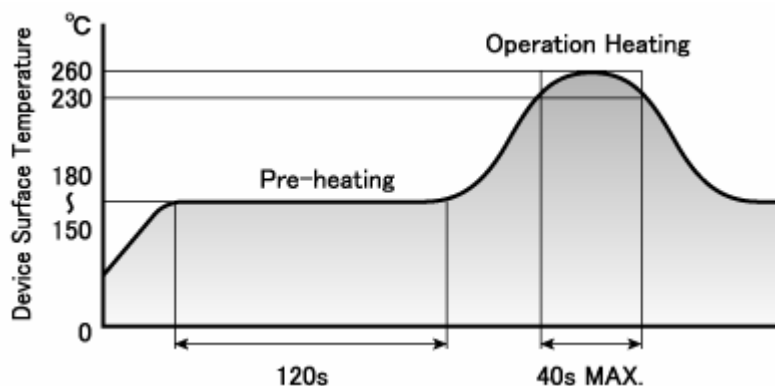
1105W-TR (Surface Mount)



1105W-RR (Reverse Mount)



Reflow Soldering Conditions



- 1) The above profile temperature gives the maximum temperature of the LED resin surface. Please set the temperature so as to avoid exceeding this range.
- 2) Total times of reflow soldering process shall be no more than 2 times. When the second reflow soldering process is performed, intervals between the first and second reflow should be short as possible (while allowing some time for the component to return to normal temperature after the first reflow) in order to prevent the LED from absorbing moisture.
- 3) Temperature fluctuation to the LED during the pre-heating process shall be minimized.

Manual Soldering Conditions

Iron tip temp. 350 °C (MAX.)

Soldering time and frequency 3 s (MAX.)
1 time (MAX.)

Reliability Testing Result

Reliability Testing Result	Applicable Standard	Testing Conditions	Duration	Failure
Room Temp. Operating Life	EIAJ ED-4701/100(101)	Ta = 25°C, If = Maxium Rated Current	1,000 h	0/25
Resistance to Soldering Heat	EIAJ ED-4701/300(301)	Pre-heating : 150~180°C 120s Max. Operation Heating : 230°C 40s Max. Peak Temperature : 260°C	Twice	0/25
Temperature Cycling	EIAJ ED-4701/100(105)	Minimum Rated Storage Temperature(30min) ~Normal Temperature(15min) ~Maximum Rated Storage Temperature(30min) ~Normal Temperature(15min)	200 cycles	0/25
High Temp. Operating Life	EIAJ ED-4701/100(101)	Ta = 100°C, If = 5mA	1,000 h	0/25
Humidity Temp. Operating Life	EIAJ ED-4701/100(102)	Ta = 60±2°C, RH = 90±5%, If = 30mA	1,000 h	0/25
High Temp. Storage Life	EIAJ ED-4701/200(201)	Ta = Maximum Rated Storage Temperature	1,000 h	0/25
Low Temp. Storage Life	EIAJ ED-4701/200(202)	Ta = Minimum Rated Storage Temperature	1,000 h	0/25
Vibration, Variable Frequency	EIAJ ED-4701/400(403)	98.1m/s ² (10G), 100 ~ 2KHz sweep for 20min., XYZ each direction	2 h	0/10

Failure Criteria

Items	Symbols	Conditions	Failure criteria
Luminous Intensity	Iv	If Value of each product Luminous Intensity	Testing Min. Value < Spec. Min. Value x 0.5
Forward Voltage	V _F	If Value of each product Forward Voltage	Testing Max. Value ≥ Spec. Max. Value x 1.2
Reverse Current	I _R	V _R = Maximum Rated Reverse Voltage V	Testing Max. Value ≥ Spec. Max. Value x 2.5
Cosmetic Appearance	-	-	Occurrence of notable decoloration, deformation and cracking

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